



Enable max = 7V
 Pull below 1.18V to disable
 Float or pull-high to enable

Orderable: N/A	Designed for: Sumitomo-Denko	Mod. Date: 1/21/2015	<p>TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2014</p>
TID #: ChangeMe!	Project Title: 3.3V@5A Low Noise Buck Converter		
Number: PMP10900	Rev: A	Sheet: 1 of 1	
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By: R Manack	File: PMP10900_Sheet1.SchDoc	Contact: http://www.ti.com/support	

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